

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-2. (Canceled)

3. (Previously Presented) The manufacturing process of conductive composition as in claim 35, wherein said first slurry and said second slurry have substantially the same composition.

4-16. (Canceled)

17. (Previously Presented) The manufacturing process of conductive composition as in claim 35, wherein said conductive composition is a conductive paste to form an electrode on ceramic dielectric substrate.

18-25. (Canceled)

26. (Previously Presented) The manufacturing process of conductive composition as in claim 37, wherein said first slurry and said second slurry have substantially the same composition.

27-29. (Canceled)

30. (Previously Presented) The manufacturing process of conductive composition as in claim 37, wherein said conductive composition is a conductive paste to form an electrode on ceramic dielectric substrate.

31-34. (Canceled)

35. (Currently Amended) A manufacturing process of conductive composition including metal particles and ceramics particles, comprising the steps of:

providing undried metal particles having been water washed;

wetting undried said metal particles by a liquid solvent that is compatible with an organic component included in said conductive composition and is incompatible with water; and

colliding a first slurry including at least said wetted metal particles and said ceramics particles with a second slurry supplied along ~~contrary~~ a different direction from the first ~~slurry, slurry, wherein~~

~~wherein~~ an average particle size of said metal particles is 0.5 μ m or less, and

~~wherein~~ an average particle size of said ceramics particles is a quarter of or less than the average particle size of said metal particles.

36. (Currently Amended) A manufacturing process of conductive composition including metal particles and ceramics particles, comprising the steps of:

providing undried metal particles having been water washed;

wetting undried said metal particles by a liquid solvent that is compatible with an organic component included in said conductive composition and is incompatible with water; and

colliding a first slurry including at least said wetted metal particles and said ceramics particles with a second slurry supplied along ~~contrary~~ a different direction from the first ~~slurry, slurry, wherein~~

~~wherein~~ an average particle size of said ceramics particles is less than that of said metal particles, and

~~wherein~~ an average particle size of said metal particles is 0.5 μ m or less.

37. (Currently Amended) A manufacturing process of conductive composition including metal particles and ceramics particles, comprising the steps of:

providing undried metal particles having been water washed;

wetting undried said metal particles by a liquid solvent that is compatible with an organic component included in said conductive composition and is incompatible with water; and

colliding a first slurry including at least said wetted metal particles and said ceramics particles with a second slurry supplied along ~~contrary~~ a different direction from the first ~~slurry, slurry, wherein~~

~~wherein~~ said metal particles are Ni or Ni content ~~compound, and compound,~~

~~wherein~~ an average particle size of said metal particles is 0.5 μ m or less, and

~~wherein~~ an average particle size of said ceramics particles is a quarter of or less than the average particle size of said metal particles.

38. (Currently Amended) A manufacturing process of conductive composition including metal particles and ceramics particles, comprising the steps of:

providing undried metal particles having been water washed;

wetting undried said metal particles by a liquid solvent that is compatible with an organic component included in said conductive composition and is incompatible with water; and

colliding a first slurry including at least said wetted metal particles and said ceramics particles with a second slurry supplied along ~~contrary~~ a different direction from the first ~~slurry, slurry, wherein~~

~~wherein~~ an average particle size of said metal particles is 0.5 μ m or less, and

~~wherein~~ an average particle size of said ceramics particles is a half of or less than the average particle size of said metal particles.

39. (Currently Amended) A manufacturing process of conductive composition including metal particles and ceramics particles, comprising the steps of:

providing undried metal particles having been water washed;

wetting undried said metal particles by a liquid solvent that is compatible with an organic component included in said conductive composition and is incompatible with water; and

colliding a first slurry including at least said wetted metal particles and said ceramics particles with a second slurry supplied along ~~contrary~~ a different direction from the first ~~slurry, slurry, wherein~~

~~wherein~~ said metal particles are Ni or Ni content ~~compound; and~~ compound,

~~wherein~~ an average particle size of said metal particles is 0.5 μ m or less, and

~~wherein~~ an average particle size of said ceramics particles is a half of or less than the average particle size of said metal particles.